

## Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Breakdown Voltage	30	V <sub>P</sub>
Input Control Current	100	mA
Peak (10ms)	1	A
Power Dissipation		
Input <sup>1</sup>	150	mW
Phototransistor <sup>2</sup>	150	mW
Isolation Voltage, Input to Output	3750	V <sub>rms</sub>
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

<sup>1</sup> Derate linearly 1.33mW / °C

<sup>2</sup> Derate linearly 2mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

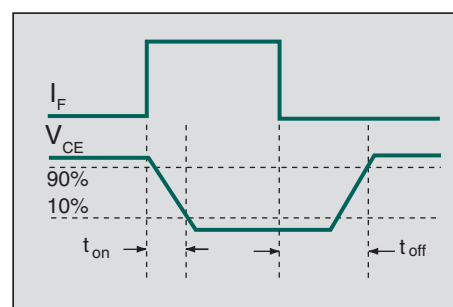
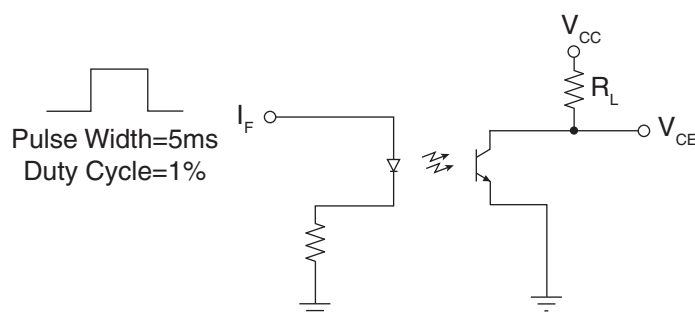
## Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Typ	Max	Units
<b>Output Characteristics</b>						
Phototransistor Breakdown Voltage	I <sub>C</sub> = 10μA	BV <sub>CEO</sub>	30	90	-	V
Phototransistor Dark Current	V <sub>CEO</sub> = 5V, I <sub>F</sub> = 0mA	I <sub>CEO</sub>	-	10	500	nA
Saturation Voltage	I <sub>C</sub> = 2mA, I <sub>F</sub> = 1mA	V <sub>CE(sat)</sub>	-	0.3	0.5	V
Current Transfer Ratio	I <sub>F</sub> = 1mA, V <sub>CE</sub> = 0.5V	CTR	33	300	1000	%
Output Capacitance	25V, f = 1MHz	C <sub>OUT</sub>	-	6	-	pF
<b>Input Characteristics</b>						
Input Control Current	I <sub>C</sub> = 0.33mA, V <sub>CE</sub> = 0.5V	I <sub>F</sub>	-	-	1	mA
Input Voltage Drop	I <sub>F</sub> = 5mA	V <sub>F</sub>	0.9	1.2	1.4	V
<b>Common Characteristics</b>						
Capacitance, Input to Output	-	C <sub>I/O</sub>	-	3	-	pF

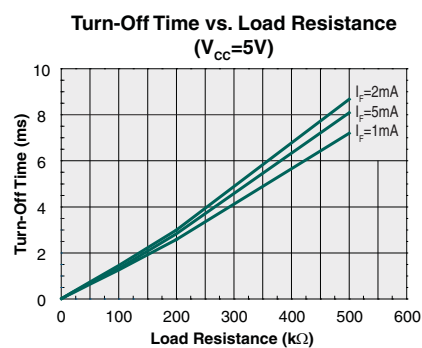
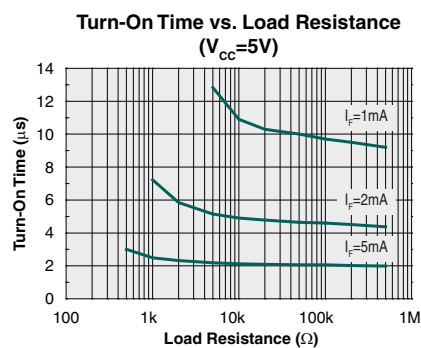
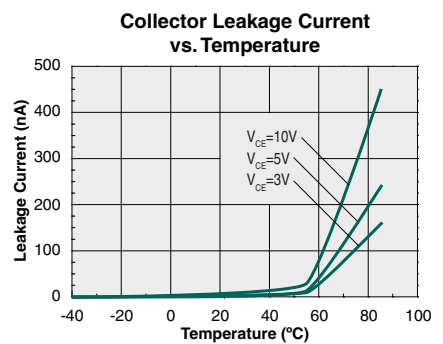
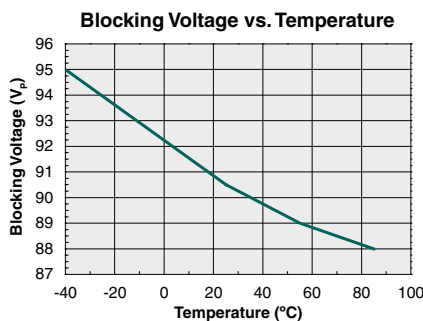
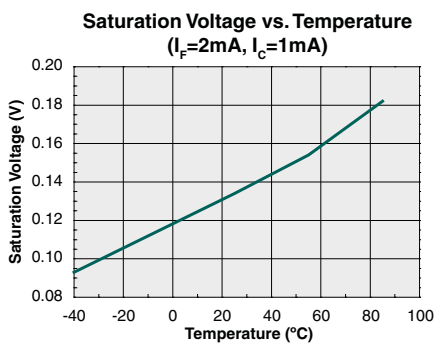
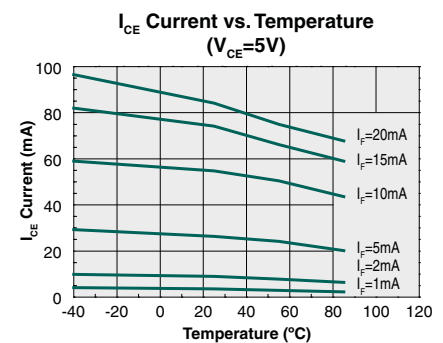
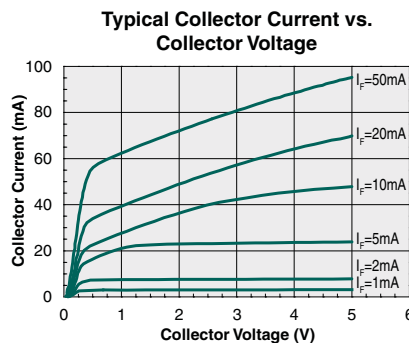
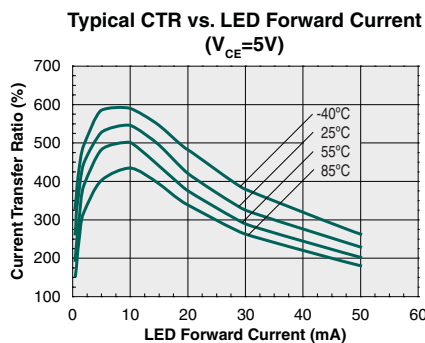
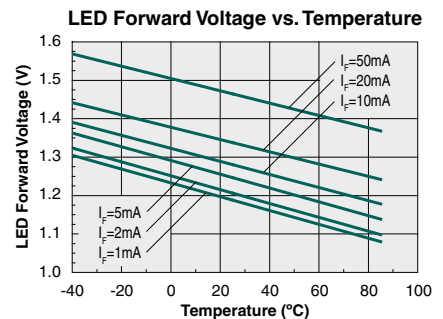
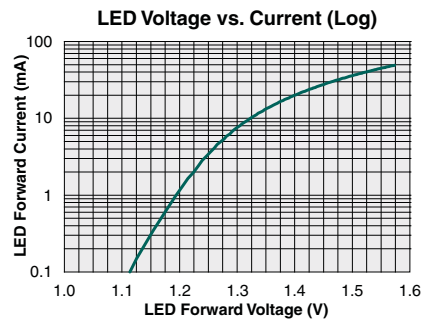
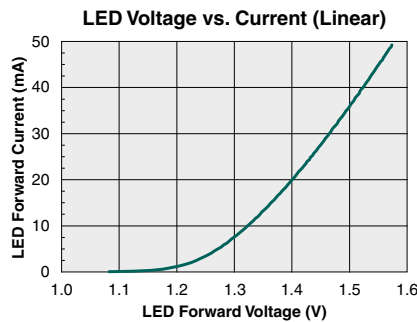
## Switching Characteristics @ 25°C

Characteristic	Symbol	Test Condition	Typ	Units
Turn-On Time	t <sub>on</sub>	V <sub>CC</sub> =5V, I <sub>F</sub> =2mA, R <sub>L</sub> =1KΩ	7	μs
Turn-Off Time	t <sub>off</sub>		20	

Switching Time Test Circuit



# PERFORMANCE DATA @25°C (Unless Otherwise Noted)\*



\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

## Manufacturing Information

### Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
LDA200 / LDA200S	MSL 1

### ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

### Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
LDA200 / LDA200S	250°C for 30 seconds

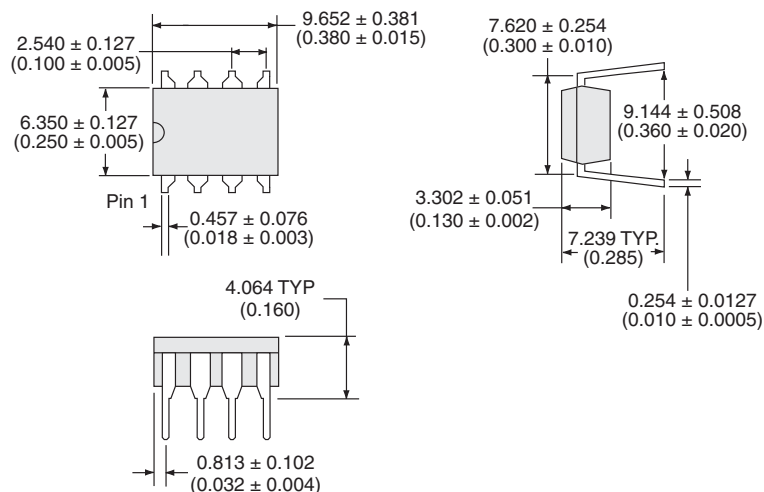
### Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

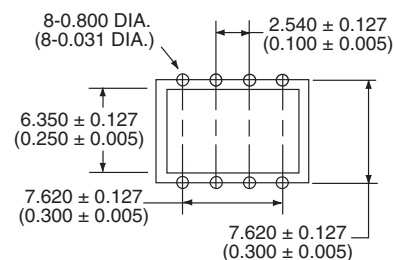


## Mechanical Dimensions

### LDA200

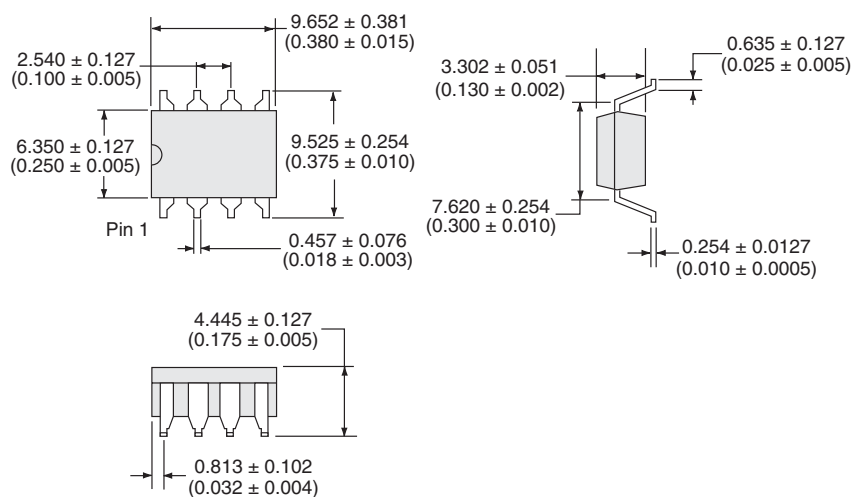


#### PCB Hole Pattern

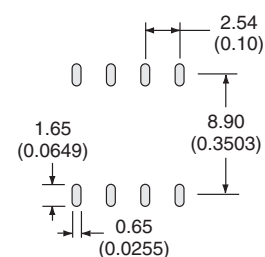


Dimensions  
mm  
(inches)

### LDA200S

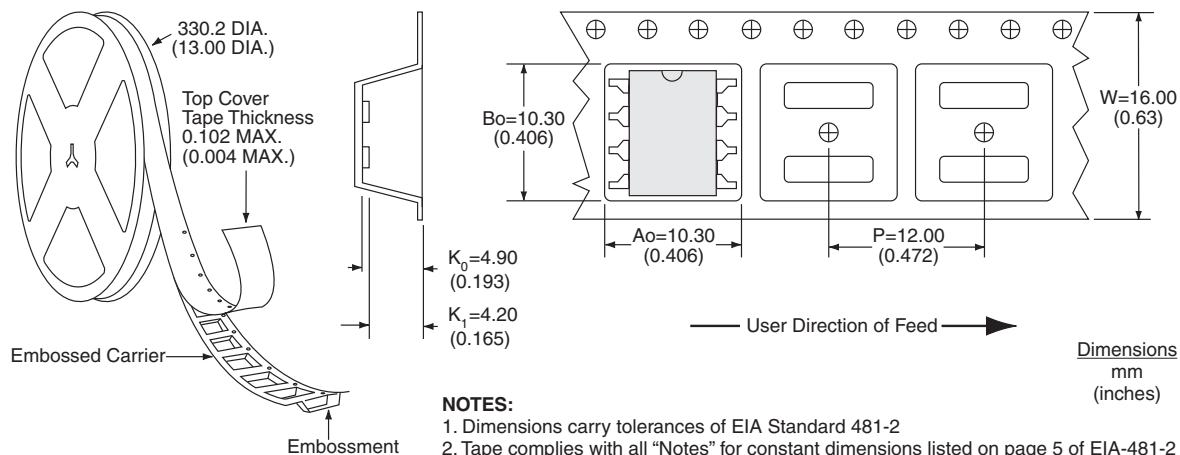


#### PCB Land Pattern



Dimensions  
mm  
(inches)

## LDA200STR Tape & Reel



**For additional information please visit our website at: [www.ixysic.com](http://www.ixysic.com)**

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